

Amendments to the Claims

This listing of claims will replace all prior versions, and listing, of claims in the application:

1. (Currently Amended) A method for bonding an integrated circuit device to a glass substrate comprising:

placing a protecting circuit, connecting with an external circuit, on the glass substrate;

[[a)] providing a melting device with a first laser device and a second laser device;

[[b)] melting a predetermined portion of the protecting circuit by the first laser device, and melting a predetermined portion of the glass substrate by the ~~melting~~ second laser device; and

[[c)] bonding the integrated circuit device on the glass substrate.

2. (Cancelled)

3. (Cancelled)

4. (Original) The method as claimed in claim 1, wherein the integrated circuit device comprises a driver circuit, a connecting wire, and a main substrate, and the connecting wire is in contact with the predetermined portion, melted by the melting device, of the glass substrate when the integrated circuit device is bonded to the glass substrate.

5. (Original) The method as claimed in claim 4, wherein the connecting wire is

bonded to the protecting circuit of the glass substrate via an adhesive and a plurality of conductive particles.

6. (Original) The method as claimed in claim 1, wherein the predetermined portion of the glass substrate is located at edges of the glass substrate.

7. (Currently Amended) A method for bonding an integrated circuit device, having a first portion and a second portion, to a glass substrate comprising:

(a) bonding ~~[[one]]~~ the first portion of the integrated circuit device to a ~~predetermined portion~~ of the glass substrate so that a gap is formed between the ~~[[other]]~~ second portion of the integrated circuit device and an edge of the glass substrate; and

(b) introducing resin into the gap so that the resin covers the ~~predetermined portion edge~~ of the glass substrate and the integrated circuit device cannot be damaged by the edge of the glass substrate due to the resin.

8. (Original) The method as claimed in claim 7, wherein the resin is cured by ultraviolet light.

9. (Cancelled)

10 (Original) The method as claimed in claim 7, wherein the integrated circuit device comprises a driver circuit, a connecting wire, and a main substrate, and the connecting wire is not in contact with the predetermined portion of the glass substrate due to the resin when the integrated circuit device is bonded to the glass substrate.

A¹ 11. (Original) The method as claimed in claim 10, wherein a protecting circuit, connecting with an external circuit, is disposed on the glass substrate, and the connecting wire is bonded to the protecting circuit of the glass substrate via an adhesive and a plurality of conductive particles.
